

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Akihiko ENDO et al.

Serial No : Not Yet Assigned (National Stage of PCT/JP2004/012633)

I.A. Filed : September 1, 2004

For : METHOD FOR MANUFACTURING BONDED WAFER

**PRELIMINARY AMENDMENT**

Commissioner of Patents  
U.S. Patent and Trademark Office  
Customer Service Window, Mail Stop \_\_\_\_\_  
Randolph Building  
401 Dulany Street  
Alexandria, VA 22314

Sir:

Prior to calculation of fees and the examination of the above-identified patent application on the merits, the Examiner is respectfully requested to amend the claims as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.